3D TSV ASSEMBLY METHOD FOR MASS REFLOW

ABSTRACT

[0036] Disclosed herein is a method that includes picking up a plate with a nozzle, the plate including at least one opening to allow air to flow therethrough. The method includes picking up a die with the nozzle such that the plate is located between the nozzle and the die. The method includes placing the die and the plate onto a device, substrate or another die such that the plate is located on top of the die. The method includes heating the device, substrate or another die and the die in a heat chamber while the plate remains on top of the die to permanently attach the die to the device, substrate or another die. Further disclosed herein is an assembly system configured to perform a method that utilizes the plate and die combination for attaching the die to a device, substrate or another die by heating.

[FIG. 1a and 1b]